form of an organic or inorganic per compound, although other oxidizing agents, such as hydroxylamine for example, may be used.

Please delete the paragraph labeled [0013] on page 4 and replace it with the replacement paragraph set forth below. A marked copy of the replacement paragraph appears as Item 2 in the Appendix hereto.

The composition provides very desirable material removal rates, for example, up to 15,000 Angstroms (Å) per minute, in a CMP process. This removal rate is so good that it may be desirable to adjust the composition or the CMP process to bring the rate down to a level suitable for certain applications, such as the CMP of very thin films, for example, a copper film of about 3000 Å in thickness. The composition is effective when used in conventional CMP processes, as well as CMP processes having relatively low carrier pressures. Substrates polished using the composition show good uniformity values, as reflected by relatively low within-wafer nonuniformity percentages. For example, in one example provided herein, the within-wafer nonuniformity of the polished substrate was about 4.57 percent.

Please delete the paragraph labeled [0017] on page 5 and replace it with the replacement paragraph set forth below. A marked copy of the replacement paragraph appears as Item 3 in the Appendix hereto.

The composition generally comprises at least one oxidizing agent and at least one abrasive that is at least partially coated by a catalyst, as further described herein. Typically, the abrasive component comprises a portion of abrasive that is coated with catalyst (sometimes referred to herein as "coated abrasive") and a portion of abrasive that is not coated with catalyst (sometimes referred to herein as "normal abrasive"), although only the former need be present. For example, the abrasive may comprise a ratio of coated abrasive to normal abrasive of about 1 to about 9. Each of the components of the composition and typical, preferred, and more preferred amounts thereof, in approximate weight percent (wt. %) relative to the composition, are provided below in Table 1.